

Search Notes

Application No.

10/611,862

Examiner

Stephen W. Smoot

Applicant(s)

IWASAKI ET AL.

Art Unit

2813

SEARCHED

Class	Subclass	Date	Examiner
257	412	3/4/2004	SWS
257	413	3/4/2004	SWS
257	762	3/4/2004	SWS
257	766	3/4/2004	SWS
257	768	3/4/2004	SWS
257	769	3/4/2004	SWS
257	774	3/4/2004	SWS
438	620	3/4/2004	SWS
Updated	Above	9/20/2004	SWS

INTERFERENCE SEARCHED

Class	Subclass	Date	Examiner

**SEARCH NOTES
(INCLUDING SEARCH STRATEGY)**

	DATE	EXMR
Considered All Citations and Search Reports from Parent Applications.	3/4/2004	S.W.S., SWS
Key Words: Copper Interconnect - Multilayer Film - Layer of Platinum, Iridium, Osmium, Rhodium, Ruthenium;	3/4/2004	S.W.S., SWS
Plus Additive of Cobalt, Nickel, Palladium, Titanium;	3/4/2004	S.W.S., SWS
Contact to Source/drain or Gate; Gate Electrode Including Layer of Platinum, Iridium, Osmium, Rhodium, Ruthenium	3/4/2004	S.W.S., SWS
Updated Above Search	9/20/2004	S.W.S., SWS
Search Tools - EAST (attached): USPAT; US PG PUBS; Derwent; EPO; JPO; IBM TDB	3/4/2004 9-20-04	SWS S.W.S.